Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards	© Copy	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Co											als and M	fg Informa	tion		
Semilar Free	nformation	•													
Product Env-Stewards	Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
Product-Env-Stewards												2023-06-	08		
Authorized Representative* Product Enviro Compliance Requester Item Number Mfr Item Number M	e			Title - Conta	ct		P	hone - Contac	et*			Email -	Contact*		
Product Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Requester Item Number Mfr Item Number NCP1216AD65R2G PWM CURRENT-MODE CONTROLL 2023-06-08 PH1 71.85 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy T	Product-Env-Stewards				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*			
NCP1216AD65R2G PWM CURRENT-MODE CONTROLL 2023-06-08 PH1 71.85 mg	Product-Env-Stewards Prod				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	equester Item Nur	Number	Mfr Item N	Number	Mfr Item Name			Effective Date	Version	N	Innufacturing Site	V	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments			NCP1216	AD65R2G	PWM CURRENT-	MODE CONTR	OLL	2023-06-08		P	H1	7	1.85	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				main al Daga	Allow	CTD 020 MCL I	Datina	Dook Droo	aga Dady T		May Time at Peak	Tommount	una Niuma	han of Deflow Cva	Jac
Comments					Alloy J-	-81D-020 MSL F	Kanng		ess Body 1	T *				ber of Reflow Cyc	ries
	atte 1111 (511) - an	annealeu	C	Alloy	1			200		<u> </u> C	30	secon	18 3		
	time at	neals townswats J	uning geld	lanina ia 10-1	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg		Epoxy resin	proprietary data		0.24	mg
			Supplier	Ethylene dimethacrylate	97-90-5		0.12	mg
			Supplier	Silver (Ag)	7440-22-4		1.92	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.12	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.2257	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.4441	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Cu	0.04	mg	Supplier	Copper (Cu)	7440-50-8		0.04	mg